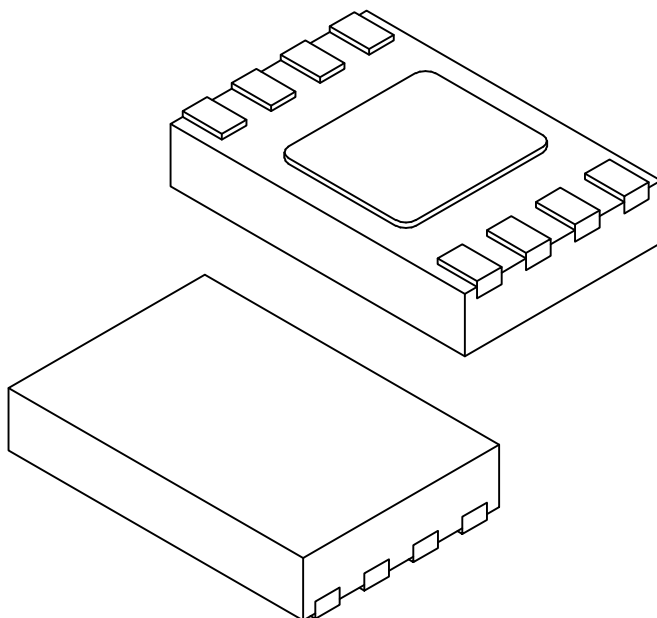


8-Lead Ultra Thin Plastic Dual Flat, No Lead Package (Q4B) - 2x3 mm Body [UDFN] Atmel Legacy Global Package Code YNZ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| | | Units | MILLIMETERS | | |
|-------------------------|----|-----------|-------------|------|-----|
| Dimension Limits | | | MIN | NOM | MAX |
| Number of Terminals | N | 8 | | | |
| Pitch | e | 0.50 BSC | | | |
| Overall Height | A | 0.50 | 0.55 | 0.60 | |
| Standoff | A1 | 0.00 | 0.02 | 0.05 | |
| Terminal Thickness | A3 | 0.152 REF | | | |
| Overall Length | D | 2.00 BSC | | | |
| Exposed Pad Length | D2 | 1.40 | 1.50 | 1.60 | |
| Overall Width | E | 3.00 BSC | | | |
| Exposed Pad Width | E2 | 1.20 | 1.30 | 1.40 | |
| Terminal Width | b | 0.18 | 0.25 | 0.30 | |
| Terminal Length | L | 0.25 | 0.35 | 0.45 | |
| Terminal-to-Exposed-Pad | K | 0.20 | - | - | |

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.